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mos integrated circuit $\mu PD72870B$

IEEE1394 1-CHIP OHCI HOST CONTROLLER

The μ PD72870B is the LSI which integrated OHCI-Link and PHY function into a single chip.

The μ PD72870B complies with the P1394a draft 2.0 specifications and the OpenHCI IEEE1394 1.0, and works up to 400 Mbps.

It makes design so compact for PC and PC card application.

FEATURES

- Compliant with Link Layer Services as defined in 1394 Open Host Controller Interface specification release 1.0
- Compliant with Physical Layer Services as defined in P1394a draft 2.0 (Data Rate 100/200/400 Mbps)
- Numbers of supported port (1, 2, 3 ports) are selectable
- Compliant with protocol enhancement as defined in P1394a draft 2.0
- Modular 32-bit host interface compliant to PCI Specification release 2.1
- Support PCI-Bus Power Management Interface Specification release 1.1
- · Modular 32-bit host interface compliant to Card Bus Specification
- Cycle Master and Isochronous Resource Manager capable
- Built-in FIFOs for isochronous transmit (1024 bytes), asynchronous transmit (1024 bytes), and receive (2048 bytes)
- 32-bit CRC generation and checking for receive/transmit packets
- · 4 isochronous transmit DMAs and 4 isochronous receive DMAs supported
- 32-bit DMA channels for physical memory read/write
- Clock generation by 24.576 MHz X'tal
- · Internal control and operational registers direct-mapped to PCI configuration space
- 2-wire Serial EEPROM[™] interface supported
- · Separate power supply Link and PHY
- Programmable latency timer from serial EEPROM in Cardbus mode (CARD_ON = 1)

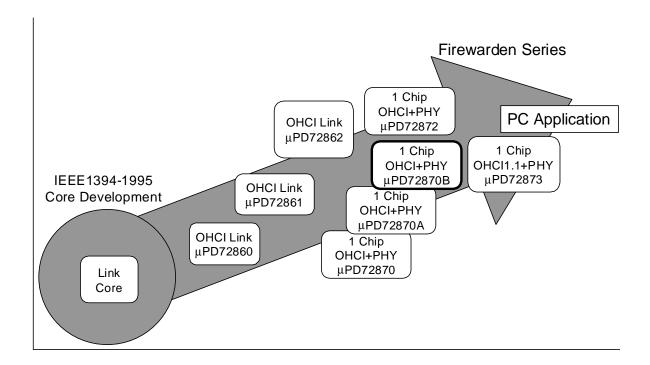
ORDERING INFORMATION

Part number	Package
μPD72870BGM-8ED	160-pin plastic LQFP (Fine pitch) (24 x 24)

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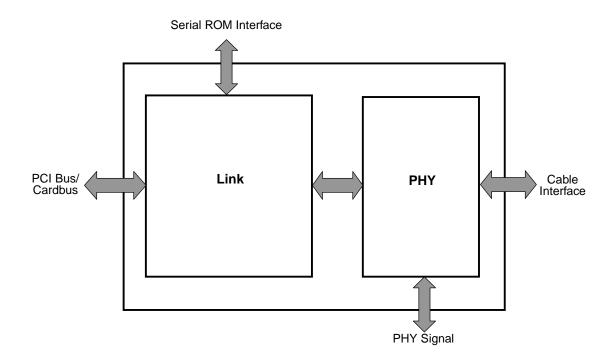
Firewarden™ PRODUCT EVOLUTION



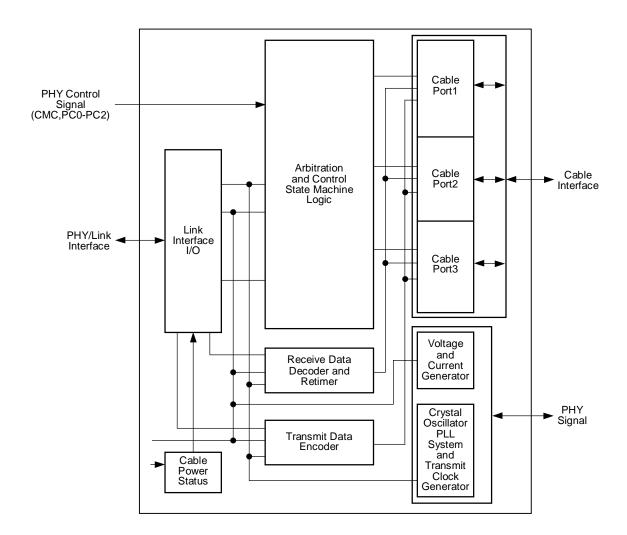


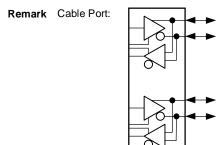
BLOCK DIAGRAMS

Top Block Diagram



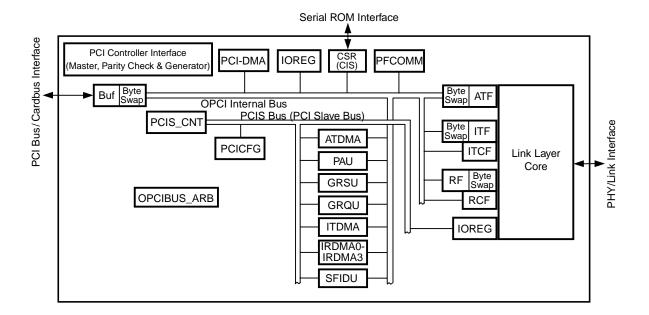
PHY Block Diagram







Link Block Diagram



ATDMA : Asynchronous Transmit DMA ATF : Asynchronous Transmit FIFO

CIS : CIS Register

CSR : Control and Status Registers

IOREG : IO Registers

IRDMA : Isochronous Receive DMA

ITCF : Isochronous Transmit Control FIFO

ITDMA : Isochronous Transmit DMA
ITF : Isochronous Transmit FIFO
OPCIBUS_ARB : OPCI Internal Bus Arbitration

PAU : Physical Response and Request Unit

PCICFG : PCI Configuration Registers

PCIS_CNT : PHY Control Isochronous Control

PFCOMM : Pre Fetch Command FIFO RCF : Receive Control FIFO

RF : Receive FIFO SFIDU : Self-ID DMA

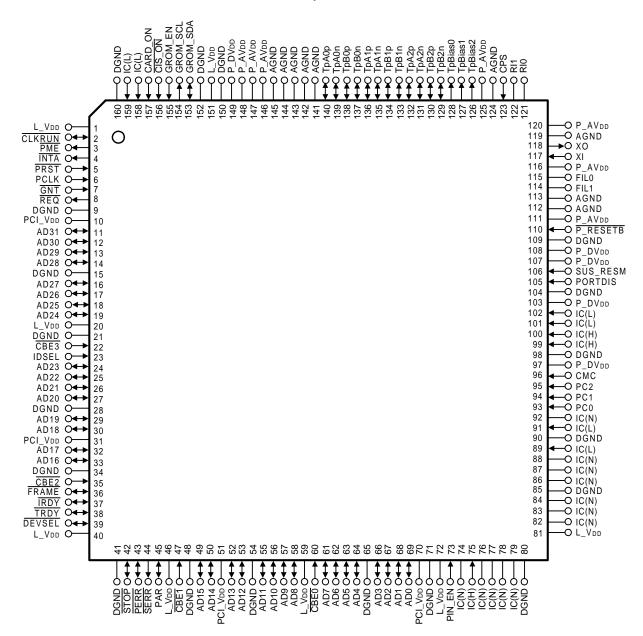


PIN CONFIGURATION

• 160-pin plastic LQFP (Fine pitch) (24 x 24)

 μ PD72870BGM-8ED

Top View





PIN NAME

 CBE0-CBE3
 : Command/Byte Enables
 P_AVDD
 : PHY Analog VDD

 CIS_ON
 : CIS Register ON
 P_DVDD
 : PHY Digital VDD

 CLKRUN
 : PCICLK Running

 P_RESETB
 : PHY Power on Reset Input

CPS : Cable Power Status Input RI0 : Resistor0 for Reference Current Setting

DEVSEL : Device Select RI1 : Resistor1 for Reference Current Setting

DGND : Digital GND SERR : System Error FIL0 : APLL Filter GND STOP : PCI Stop

FIL1 : APLL Filter Terminal SUS_RESM : Suspend/Resume Function Select

 FRAME
 : Cycle Frame
 TpA0n
 : Port-1 Twisted Pair A Negative Input/Output

 GNT
 : Bus_master Grant
 TpA0p
 : Port-1 Twisted Pair A Positive Input/Output

 GROM_EN
 : Serial EEPROM Enable
 TpA1n
 : Port-2 Twisted Pair A Negative Input/Output

 GROM_SCL
 : Serial EEPROM Clock Output
 TpA1p
 : Port-2 Twisted Pair A Positive Input/Output

GROM_SDA : Serial EEPROM Data Input / Output TpA2n : Port-3 Twisted Pair A Negative Input/Output IC(H) : Internally Connected (High Clamped) TpA2p : Port-3 Twisted Pair A Positive Input/Output IC(L) : Internally Connected (Low Clamped) TpB0n : Port-1 Twisted Pair B Negative Input/Output

IC(N) : Internally Connected (Open) TpB0p : Port-1 Twisted Pair B Positive Input/Output

 IDSEL
 : ID Select
 TpB1n
 : Port-2 Twisted Pair B Negative Input/Output

 INTA
 : Interrupt
 TpB1p
 : Port-2 Twisted Pair B Positive Input/Output

 IRDY
 : Initiator Ready
 TpB2n
 : Port-3 Twisted Pair B Negative Input/Output

L_Vdd : Vdd for Link Digital Core and Link I/Os TpB2p : Port-3 Twisted Pair B Positive Input/Output

PAR : Parity TpBias0 : Port-1 Twisted Pair Bias Voltage Output
PC0-PC2 : Power Class Input TpBias1 : Port-2 Twisted Pair Bias Voltage Output
PCI_VDD : VDD for PCI_I/Os TpBias2 : Port-3 Twisted Pair Bias Voltage Output

 PCLK
 : PCI Clock
 TRDY
 : Target Ready

 PERR
 : Parity Error
 XI
 : X'tal XI

 PIN_EN
 : Pin Enable Input
 XO
 : X'tal XO



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1. PIN FUNCTIONS

1.1 PCI/Cardbus Interface Signals: (52 pins)

(1/2)

Name	I/O	Pin No.	lol	Volts(V)	Function	
PAR	I/O	45	PCI/Cardbus	5/3.3	Parity is even parity across AD0-AD31 and CBE0-	Link ^{*1}
					CBE3. It is an input when AD0-AD31 is an input; it	
					is an output when AD0-AD31 is an output.	
AD0-AD31	I/O	11-14,16-19,	PCI/Cardbus	5/3.3	PCI Multiplexed Address and Data	Link
		24-27,29,30,			·	
		32,33,49,50,				
		52,53,55-58,				
		61-64,66-69				
CBE0-CBE3	I	22,35,47,60	-	5/3.3	Command/Byte Enables are multiplexed Bus	Link
					Commands & Byte enables.	
FRAME	I/O	36	PCI/Cardbus	5/3.3	Frame is asserted by the initiator to indicate the	Link
					cycle beginning and is kept asserted during the	
					burst cycle. If Cardbus mode (CARD_ON = 1), this	
					pin should be pulled up to V _{DD} .	
TRDY	I/O	38	PCI/Cardbus	5/3.3	Target Ready indicates that the current data phase	Link
					of the transaction is ready to be completed.	
IRDY	I/O	37	PCI/Cardbus	5/3.3	Initiator Ready indicates that the current bus	Link
					master is ready to complete the current data phase.	
					During a write, its assertion indicates that the	
					initiator is driving valid data onto the data bus.	
					During a read, its assertion indicates that the	
					initiator is ready to accept data from the currently-	
					addressed target.	
REQ	0	8	PCI/Cardbus	5/3.3	Bus_master Request indicates to the bus arbiter	Link
					that this device wants to become a bus master.	
GNT	1	7	-	5/3.3	Bus_master Grant indicates to this device that	Link
					access to the bus has been granted.	
IDSEL	I	23	-	5/3.3	Initialization Device Select is used as chip select	Link
					for configuration read/write transaction during the	
					phase of device initialization. If Cardbus mode	
					(CARD_ON = 1), this pin should be pulled up to	
					V _{DD} .	



Name	I/O	Pin No.	loL	Volts(V)	Function	
DEVSEL	I/O	39	PCI/Cardbus	5/3.3	Device Select when actively driven, indicates that	Link
					the driving device has decoded its address as the	
					target of the current access.	
STOP	I/O	42	PCI/Cardbus	5/3.3	PCI Stop when actively driven, indicates that the	Link
					target is requesting the current bus master to stop	
					the transaction.	
PME	0	3	PCI/Cardbus	5/3.3	PME Output for power management enable.	Link
CLKRUN	I/O	2	PCI/Cardbus	5/3.3	PCICLK Running as input, to determine the status	Link
					of PCLK; as output, to request starting or speeding	
					up clock.	
INTA	0	4	PCI/Cardbus	5/3.3	Interrupt the PCI interrupt request A.	Link
PERR	I/O	43	PCI/Cardbus	5/3.3	Parity Error is used for reporting data parity errors	Link
					during all PCI transactions, except a Special Cycle.	
					It is an output when AD0-AD31 and PAR are both	
					inputs. It is an input when AD0-AD31 and PAR are	
					both outputs.	
SERR	0	44	PCI/Cardbus	5/3.3	System Error is used for reporting address parity	Link
					errors, data parity errors during the Special Cycle,	
					or any other system error where the effect can be	
					catastrophic. When reporting address parity errors,	
					it is an output.	
PRST	1	5	-	5/3.3	Reset PCI reset	Link
PCLK	I	6	-	5/3.3	PCI Clock 33 MHz system bus clock.	Link

1.2 Cable Interface Signals: (15 pins)

(1/2)

Name	I/O	Pin No.	loь	Volts(V)	Function	(1/2
ТрА0р	I/O	140	-	-	Port-1 Twisted Pair A Positive Input/Output Note	PHY Analog *2
TpA0n	I/O	139	-	-	Port-1 Twisted Pair A Negative Input/Output Note	PHY Analog
ТрВ0р	I/O	138	-	-	Port-1 Twisted Pair B Positive Input/Output Note	PHY Analog
TpB0n	I/O	137	-	=	Port-1 Twisted Pair B Negative Input/Output Note	PHY Analog
TpA1p	I/O	136	-	-	Port-2 Twisted Pair A Positive Input/Output Note	PHY Analog
TpA1n	I/O	135	-	-	Port-2 Twisted Pair A Negative Input/Output Note	PHY Analog
ТрВ1р	I/O	134	-	=	Port-2 Twisted Pair B Positive Input/Output Note	PHY Analog
TpB1n	I/O	133	-	-	Port-2 Twisted Pair B Negative Input/Output Note	PHY Analog
TpA2p	I/O	132	-	-	Port-3 Twisted Pair A Positive Input/Output Note	PHY Analog
TpA2n	I/O	131	-	-	Port-3 Twisted Pair A Negative Input/Output Note	PHY Analog
ТрВ2р	I/O	130	-	-	Port-3 Twisted Pair B Positive Input/Output Note	PHY Analog
TpB2n	I/O	129	-	-	Port-3 Twisted Pair B Negative Input/Output Note	PHY Analog

Note If unused port, please refer to 4.1.4 Unused Ports.



(2/2)

Name	I/O	Pin No.	loL	Volts(V)	Function	
PORTDIS	I	105			Port Disable SUS_RESM = 1 This selected state will be loaded to Disabled bit which allocated PHY register Port Status Page. 1:Disable At this time, all ports will be disabled. SUS_RESM = 0	PHY Digital ^{*3}
SUS_RESM	I	106			PORTDIS has no effect. Suspend/Resume Function Select 1: Suspend/Resume On (P1394a draft 2.0 compliant) 0: Suspend/Resume Off (P1394a draft 1.3 compliant)	PHY Digital
CPS	- 1	123	-	-	Cable Power Status Input Note	PHY Digital

Note Please refer to 4.1.3 CPS.

1.3 PHY Signals: (9 pins)

Name	I/O	Pin No.	loL	Volts(V)	Function			
TpBias0	0	128	-	-	Port-1 Twisted Pair Bias Voltage Output Note 1	PHY Analog		
TpBias1	0	127	-	-	Port-2 Twisted Pair Bias Voltage Output Note 1	PHY Analog		
TpBias2	0	126	-	-	Port-3 Twisted Pair Bias Voltage Output Note 1 PHY			
RI0	-	121	-	-	Resistor0 for Reference Current Setting Note 2	PHY Analog		
RI1	-	122	-	ı	- Resistor1 for Reference Current Setting Note 2			
FIL1	-	114	-	-	APLL Filter Terminal (No need to assemble)	PHY Analog		
FIL0	-	115	-	-	APLL Filter GND (No need to assemble)	PHY Analog		
XI	I	117	-	-	X'tal XI	PHY Analog		
XO	0	118	-	-	X'tal XO	PHY Analog		

Notes 1. If unused port, please refer to 4.1.4 Unused Ports.

2. Please refer to 4.6 RIO, RI1.

1.4 PHY Control Signals: (5 pins)

Name	I/O	Pin No.	loL	Volts(V)	Function	
PC0-PC2	I	93-95	-	3.3	Power Class Input Note 1	PHY Digital
CMC	ı	96	-	3.3	Configuration Manager Capable Note 1	PHY Digital
P_RESETB	ı	110			PHY Power on Reset Input Note 2	PHY Digital

Notes 1. Please refer to 4.4 PC0-PC2, CMC.

2. Please refer to 4.5 P_RESETB.



1.5 PCI/Cardbus Select Signals: (2 pins)

Name	I/O	Pin No.	loL	Volts(V)		Fui	nction			
CARD_ON	1	157	-	3.3	PCI/Card Se	PCI/Card Select (1:Cardbus, 0:PCI bus)				
CIS_ON	- 1	156	-	3.3	CIS Register	CIS Register ON				
					CARD_ON	CIS_ON	CIS	PME		
					0	1	Off	PME		
					0	0	On	CSTSCHG		
					1	X	On	CSTSCHG		

1.6 Serial ROM Interface Signals: (3 pins)

Name	I/O	Pin No.	Іоь	Volts(V)	Function	
GROM_SDA	I/O	153	6 mA	3.3	Serial EEPROM Data Input / Output	Link
GROM_SCL	0	154	6 mA	3.3	Serial EEPROM Clock Output	Link
GROM_EN	I	155	-	3.3	Serial EEPROM Enable	Link
					(1: GUID Load enabled, 0: GUID Load disabled)	

1.7 Miscellaneous Signal: (1 pin)

Name	I/O	Pin No.	loL	Volts(V)	Function	
PIN_EN	- 1	73	-	5/3.3	Pin Enable Input (High clamped)	Link

1.8 IC: (21 pins)

Name	I/O	Pin No.	loL	Volts(V)	Function	
IC(H)	I	75	-	i	Internally Connected (High clamped)	Link
	I	99,100	1	i	Internally Connected (High clamped)	PHY Digital
IC(L)	1	89,158,159	-	-	Internally Connected (Low clamped)	Link
	ı	91,101,102	-	-	Internally Connected (Low clamped)	PHY Digital
IC(N)	-	74,76-79,82-84,86-88,92	-	i	Internally Connected (Open)	-



1.9 V_{DD}

Name	I/O	Pin No.	lol	Volts(V)	Function	
PCI_VDD	-	10,31,51,70	-	5/3.3	V _{DD} for PCI I/Os	Link
L_V _{DD}	-	1,20,40,46,59,72,81,151	-	3.3	V _{DD} for Link digital Core and	Link
					Link I/Os	
P_DV _{DD}	-	97,103,107,108,149	-	3.3	PHY digital VDD	PHY Digital
P_AV _{DD}	-	111	-	3.3	PHY PLL VDD	PHY Analog
	-	116	-	3.3	PHY PLL, OSC VDD	PHY Analog
	-	120,125	-	3.3	PHY Bias VDD	PHY Analog
	-	146-148	-	3.3	PHY Port VDD	PHY Analog

1.10 GND

Name	I/O	Pin No.	loь	Volts(V)	Function
DGND	-	9,15,21,28,34,41,48,54,	-	-	Digital GND
		65,71,80,85,90,98,104,			
		109,150,152,160			
AGND	-	112	-	-	PHY PLL GND
	-	113	-	-	PHY PLL, OSC GND
	-	119,124	-	-	PHY Bias GND
	-	141	-	-	PHY Common GND
	-	142	-	-	PHY Speed Signal GND
	-	143,144,145	-	-	PHY Port GND

[Caution]

- $^{*}1$: If the Link pin is pulled up, it should be connected to L_VdD.
- *2: If the PHY Digital pin is pulled up, it should be connected to P_DVDD.
- *3: If the PHY Analog pin is pulled up, it should be connected to P_AVDD.



2. PHY REGISTERS

2.1 Complete Structure for PHY Registers

Figure 2-1. Complete Structure of PHY Registers

	0	1	2	3	4	5	6	7
0000			Physi	cal_ID			R	PS
0001	RHB	IBR			Gap_	count		
0010		Extended (7)		Reserved		Total_	_ports	
0011		Max_speed		Reserved		De	lay	
0100	Link_active	Contender		Jitter			Pwr_class	
0101	Resume_int	ISBR	Loop	Pwr_fail	Timeout	Port_event	Enab_accel	Enab_multi
0110				Rese	rved			
0111		Page_select		Reserved		Port_	select	
1000				Register0 (p	age_select)			
1001				Register1 (p	age_select)			
1010				Register2 (p	age_select)			
1011				Register3 (p	age_select)			
1100				Register4 (p	age_select)			
1101				Register5 (p	age_select)			
1110				Register6 (p	age_select)			
1111				Register7 (p	age_select)			

Table 2-1. Bit Field Description (1/3)

Field	Size	R/W	Reset value	Description	
Physical_ID	6	R	000000	Physical_ID value selected from Self_ID period.	
R	1	R	0	If this bit is 1, the node is root.	
				1: Root	
				0: Not root	
PS	1	R		Cable power status.	
				1: Cable power on	
				0: Cable power off	
RHB	1	R/W	0	Root Hold -off bit. If 1, becomes root at the bus reset.	
IBR	1	R/W	0	Initiate bus reset.	
				Setting to 1 begins a long bus reset.	
				Long bus reset signal duration: 166 μ s.	
				Returns to 0 at the beginning of bus reset.	
Gap_count	6	R/W	111111	Gap count value.	
				It is updated by the changes of transmitting and receiving the PHY	
				configuration packet Tx/Rx.	
				The value is maintained after first bus reset.	
				After the second bus reset it returns to reset value.	



Table 2-1. Bit Field Description (2/3)

Field	Size	R/W	Reset value	Description
Extended	3	R	111	Shows the extended register map.
Total_ports	4	R	0011	Supported port number.
				0011: 3 ports
Max_speed	3	R	010	Indicate the maximum speed that this node supports.
				010: 98.304, 196.608 and 393.216 Mbps
Delay	4	R	0010	Indicate worst case repeating delay time. 144 + (2 x 20) = 184 ns
Link_active	1	R/W	1	Link active.
				1: Enable
				0: Disable
				The logical AND status of this bit and LPS.
				State will be referred to "L bit" of Self-ID Packet#0.
l				The LPS is a PHY/Link interface signal and is defined in P1394a draft 2.0. It
				is an internal signal in the μ PD72870B.
Contender	1	R/W	See	Contender.
			Description	"1" indicate this node support bus manager function. This bit will be referred
				to "C bit" of Self-ID Packet#0.
				The reset data is depending on CMC pin setting.
				CMC pin condition
				1: Pull up (Contender)
				0: Pull down (Non Contender)
Jitter	3	R	010	The difference of repeating time (MaxMin.). (2+1) x 20 = 60 ns
Pwr_class	3	R/W	See	Power class.
			Description	Please refer to IEEE1394 -1995 [4.3.4.1].
				This bit will be referred to Pwr field of Self-ID Packet#0.
				The reset data will be determined by PC0-PC2 Pin status.
Resume_int	1	R/W	0	Resume interrupt enable. When set to 1, if any one port does resume, the
				Port_event bit becomes 1.
ISBR	1	R/W	0	Initiate short (arbitrated) bus reset.
				Setting to 1 acquires the bus and begins short bus reset.
				Short bus reset signal output : 1.3 μ s
				Returns to 0 at the beginning of the bus reset.
Loop	1	R/W	0	Loop detection output.
				1: Detection
				Writing 1 to this bit clears it to 0.
				Writing 0 has no effect.
Pwr_fail	1	R/W	0	Power cable disconnect detect.
				It becomes 1 when there is a change from 1 to 0 in the CPS bit.
				Writing 1 to this bit clears it to 0.
				Writing 0 has no effect.
Timeout	1	R/W	0	Arbitration state machine time-out.
				Writing 1 to this bit clears it to 0.
				Writing 0 has no effect.



Table 2-1. Bit Field Description (3/3)

Field	Size	R/W	Reset value	Description
Port_event	1	R/W	0	Set to 1 when the Int_Enable bit in the register map of each port is 1 and
				there is a change in the ports connected, Bias, Disabled and Fault bits.
				Set to 1 when the Resume_int bit is 1 and any one port does resume.
				Writing 1 to this bit clears it to 0.
				Writing 0 has no effect.
Enab_accel	1	R/W	0	Enables arbitration acceleration.
				Ack-acceleration and Fly-by arbitration are enabled.
				1: Enabled
				0: Disabled
				If this bit changes while the bus request is pending, the operation is not
				guaranteed.
Enab_multi	1	R/W	0	Enable multi-speed packet concatenation.
				Setting this bit to 1 follows multi-speed transmission.
				When this bit is set to 0,the packet will be transmitted with the same speed
				as the first packet.
Page_select	3	R/W	000	Select page address between 1000 to 1111.
				000: Port Status Page
				001: Vendor Definition Page
				Others: Unused
Port_select	4	R/W	0000	Port Selection.
				Selecting 000 (Port Status Page) with the page selection selects the port.
				0000: Port 0
				0001: Port 1
				0010: Port 2
				Others: Unused
Reserved	-	R	000	Reserved. Read as 0.



2.2 Port Status Page (Page 000)

Figure 2-2. Port Status Page

	0	1	2	3	4	5	6	7
1000	AS	Stat	BS	Stat	Child	Connected	Bias	Disabled
1001	N	egotiated_spe	ed	Int_enable	Fault		Reserved	
1010				Rese	erved			
1011				Rese	erved			
1100				Rese	erved			
1101				Rese	erved			
1110				Rese	erved			
1111				Rese	erved			

Table 2-2. Bit Field Description

Field	Size	R/W	Reset value	Description
AStat	2	R	XX	A port status value.
				00:, 10: "0"
				01: "1", 11: "Z"
BStat	2	R	XX	B port status value.
				00:, 10: "0"
				01: "1", 11: "Z"
Child	1	R		Child node status value.
				1: Connected to child node
				0 : Connected to parent node
Connected	1	R	0	Connection status value.
				1: Connected
				0: Disconnected
Bias	1	R		Bias voltage status value.
				1: Bias voltage
				0: No bias voltage
Disabled	1	R/W	See	The reset value is set by the PORTDIS pin.
			Description	1: Disable
Negotiated_	3	R		Shows the maximum data transfer rate of the node connected to this port.
Speed				000: 100 Mbps
				001: 200 Mbps
				010: 400 Mbps
Int_enable	1	R/W	0	The Port_event is set to 1 by a change to 1 of the Connected, Bias, Disable,
				and Fault bits.
Fault	1	R/W	0	Set to 1 if an error occurs during Suspend/Resume.
				Writing 1 to this bit clears it to 0.
				Writing 0 has no effect.
Reserved	-	R	000	Reserved. Read as 0.



2.3 Vendor ID Page (Page 001)

Figure 2-3. Vendor ID Page

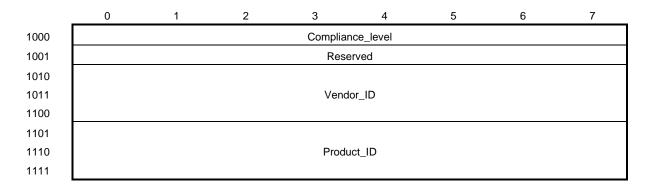


Table 2-3. Bit Field Description

Field	Size	R/W	Reset value	Description
Compliance_level	8	R	0000001	According to IEEE P1394a.
Vendor_ID	24	R	00004CH	Company ID Code value, NEC IEEE OUI.
Product_ID	24	R		Product code.
Reserved	-	R	000	Reserved. Read as 0.



3. CONFIGURATION REGISTERS

3.1 PCI Bus Mode Configuration Register (CARD_ON = Low)

	24	23 16	15 08	07 0
		ce ID		dor ID
		Class Code	Com	Revision ID
	IST	Header Type	Latency Timer	Cache Line Size
		Base Ac		040.10 2.110 0.120
		Base Ad	ddress 1	
		Base Ac	ddress 2	
		Base Ad	ddress 3	
		Base Ad	ddress 4	
		Base Ad	ddress 5	
		CardBus C	CIS Pointer	
	Subsys	stem ID	Subsysten	n Vendor ID
		Expansion Rom Bas	se Address Register	1
		000000H		Cap_Ptr
		00000	0000H	,
Max	x_Lat	Min_Gnt	Interrupt Pin	Interrupt Line
		PCI_OHC	CI_Control	
		00000	0000H	
		00000	0000H	
		00000	0000H	
		Diagnostic	c register0	
		Diagnostic	c register1	
		Diagnostic	register2	
		Diagnostic	register3	
F	Power Manager	nent Capabilities	Next_Item_Ptr	Cap_ID
D	ata	PMCSR_BSE	Power Managem	ent Control/Status
		00000	0000H	
		00000	0000H	
		00000	0000H	
		User Area (GENE	ERAL_RegisterB)	
		User Area (GENE	ERAL_RegisterC)	
		User Area (GENE	ERAL_RegisterD)	
·		00000	0000H	



3.1.1 Offset_00 Vendor ID Register

This register identifies the manufacturer of the μ PD72870B. The ID is assigned by the PCI_SIG committee.

Bits	R/W	Description
15-0	R	Constant value of 1033H.

3.1.2 Offset_02 Device ID Register

This register identifies the type of the device for the μ PD72870B. The ID is assigned by NEC Corporation.

Bits	R/W	Description
15-0	R	Constant value of 00CDH.

3.1.3 Offset_04 Command Register

The register provides control over the device's ability to generate and respond to PCI cycles.

Bits	R/W	Description
0	R	I/O enable Constant value of 0. The μ PD72870B does not respond to PCI I/O accesses.
1	R/W	Memory enable Default value of 1. It defines if the μ PD72870B responds to PCI memory
		accesses. This bit should be set to one upon power-up reset.
		0: The μ PD72870B does not respond to PCI memory cycles
		1: The μPD72870B responds to PCI memory cycles
2	R/W	Master enable Default value of 1. It enables the μ PD72870B as bus-master on the PCI-bus.
		0: The μPD72870B cannot generate PCI accesses by being a bus-master
		1: The μ PD72870B is capable of acting as a bus-master
3	R	Special cycle monitor enable Constant value of 0. The special cycle monitor is always
		disabled.
4	R/W	Memory write and invalidate enable Default value of 0. It enables Memory Write and Invalid
		Command generation.
		0: Memory write must be used
		1: The μ PD72870B, when acts as PCI master, can generate the command
5	R	VGA color palette invalidate enable Constant value of 0. VGA color palette invalidate is
		always disabled.
6	R/W	Parity error response Default value of 0. It defines if the μ PD72870B responds to $\overline{\text{PERR}}$.
		0: Ignore parity error
		1: Respond to parity error
7	R	Stepping enable Constant value of 0. Stepping is always disabled.
8	R/W	System error enable Default value of 0. It defines if the μ PD72870B responds to SERR.
		0: Disable system error checking
		1: Enable system error checking
9	R	Fast back-to-back enable Constant value of 0. Fast back-to-back transactions are only
		allowed to the same agent.
15-10	R	Reserved Constant value of 000000.



3.1.4 Offset_06 Status Register

This register tracks the status information of PCI-bus related events which are relevant to the μ PD72870B. "Read" and "Write" are handled somewhat differently.

Bits	R/W	Description
3-0	R	Reserved Constant value of 0000.
4	R	New capabilities Constant value of 1. It indicates the existence of the Capabilities List.
6,5	R	Reserved Constant value of 00.
7	R	Fast back-to-back capable Constant value of 1. It indicates that the μ PD72870B, as a target,
		cannot accept fast back-to-back transactions when the transactions are not to the same agent.
8	R/W	Signaled parity error Default value of 0. It indicates the occurrence of any "Data Parity".
		0: No parity detected (default)
		1: Parity detected
10,9	R	DEVSEL timing Constant value of 01. These bits define the decode timing for DEVSEL.
		0: Fast (1 cycle)
		1: Medium (2 cycles)
		2: Slow (3 cycles)
		3: undefined
11	R/W	Signaled target abort Default value of 0. This bit is set by a target device whenever it
		terminates a transaction with "Target Abort".
		0: The μ PD72870B did not terminate a transaction with Target Abort
		1: The μ PD72870B has terminated a transaction with Target Abort
12	R/W	Received target abort Default value of 0. This bit is set by a master device whenever its
		transaction is terminated with a "Target Abort".
		0: The μ PD72870B has not received a Target Abort
		1: The μ PD72870B has received a Target Abort from a bus-master
13	R/W	Received master abort Default value of 0. This bit is set by a master device whenever its
		transaction is terminated with "Master Abort". The μ PD72870B asserts "Master Abort" when a
		transaction response exceeds the time allocated in the latency timer field.
		0: Transaction was not terminated with a Master Abort
		1: Transaction has been terminated with a Master Abort
14	R/W	Signaled system error Default value of 0. It indicates that the assertion of SERR by the
		μPD72870B.
		0: System error was not signaled
		1: System error was signaled
15	R/W	Received parity error Default value of 0. It indicates the occurrence of any PERR.
		0: No parity error was detected
		1: Parity error was detected



3.1.5 Offset_08 Revision ID Register

This register specifies a revision number assigned by NEC Corporation for the μ PD72870B.

Bits	R/W	Description
7-0	R	Default value of 03H. It specifies the silicon revision. It will be incremented for subsequent
		silicon revisions.

3.1.6 Offset_09 Class Code Register

This register identifies the class code, sub-class code, and programming interface of the μ PD72870B.

Bits	R/W	Description
7-0	R	Constant value of 10H. It specifies an IEEE1394 OpenHCl-compliant Host Controller.
15-8	R	Constant value of 00H. It specifies an "IEEE1394" type.
23-16	R	Constant value of 0CH. It specifies a "Serial Bus Controller".

3.1.7 Offset_0C Cache Line Size Register

This register specifies the system cache line size, which is PC-host system dependent, in units of 32-bit words. The following cache line sizes are supported: 2, 4, 8, 16, 32, 64, and 128. All other values will be recognized as 0, i.e. cache disabled.

Bits	R/W	Description
7-0	R/W	Default value of 00H.

3.1.8 Offset_0D Latency Timer Register

This register defines the maximum amount of time that the μ PD72870B is permitted to retain ownership of the bus after it has acquired bus ownership and initiated a subsequent transaction.

Bits	R/W	Description
7-0	R/W	Default value of 00H. It specifies the number of PCI-bus clocks that the μ PD72870B may hold
		the PCI bus as a bus-master.

3.1.9 Offset_0E Header Type Register

Bits	R/W	Description
7-0	R	Constant value of 00H. It specifies a single function device.

3.1.10 Offset_0F BIST Register

Bits	R/W	Description
7-0	R	Constant value of 00H. It specifies whether the device is capable of Built-in Self Test.



3.1.11 Offset_10 Base Address 0 Register

This register specifies the base memory address for accessing all the "Operation registers" (i.e. control, configuration, and status registers) of the μ PD72870B, while the BIOS is expected to set this value during power-up reset.

Bits	R/W	Description
11-0	R	Constant value of 000H. These bits are "read-only".
31-12	R/W	-

3.1.12 Offset_20 Subsystem Vendor ID Register

This register identifies the subsystem that contains the NEC's μ PD72870B function. While the ID is assigned by the PCI_SIG committee, the value should be loaded into the register from the external serial ROM after power-up reset. Access to this register through PCI-bus is prohibited.

Bits	R/W	Description
15-0	R	Default value of 1033H.

3.1.13 Offset_22 Subsystem ID Register

This register identifies the type of the subsystem that contains the NEC's μ PD72870B function. While the ID is assigned by the manufacturer, the value should be loaded into the register from the external serial EEPROM after power-up reset. Access to this register through PCI-bus is prohibited.

Bits	R/W	Description
15-0	R	Default value of 0063H.

3.1.14 Offset_30 Expansion Rom Base Address Register

This register is not supported by the current implementation of the μ PD72870B.

Bits	R/W	Description
31-0	R	Reserved Constant value of 0.

3.1.15 Offset_34 Cap_Ptr Register

This register points to a linked list of additional capabilities specific to the μ PD72870B, the NEC's implementation of the 1394 OpenHCl specification.

Bits	R/W	Description	
7-0	R	Constant value of 60H. The value represents an offset into the μ PD72870B's PCI	
		Configuration Space for the location of the first item in the New Capabilities Linked List.	



3.1.16 Offset_3C Interrupt Line Register

This register provides the interrupt line routing information specific to the μ PD72870B, the NEC's implementation of the 1394 OpenHCl specification.

Bits	R/W	Description
7-0	R/W	Default value of 00H. It specifies which input of the host system interrupt controller the
		interrupt pin of the μ PD72870B is connected to.

3.1.17 Offset_3D Interrupt Pin Register

This register provides the interrupt line routing information specific to the μ PD72870B, the NEC's implementation of the 1394 OpenHCl specification.

Bits	R/W	Description	
7-0	R	Constant value of 01H. It specifies PCI INTA is used for interrupting the host system.	

3.1.18 Offset_3E Min_Gnt Register

This register specifies how long of a burst period the μ PD72870B needs, assuming a clock rate of 33 MHz. Resolution is in units of $\frac{1}{4}$ μ s. The value should be loaded into the register from the external serial EEPROM upon power-up reset, and access to this register through PCI-bus is prohibited.

Bits	R/W	Description	
7-0	R	Default value of 00H. Its value contributes to the desired setting for Latency Timer value.	

3.1.19 Offset_3F Max_Lat Register

This register specifies how often the μ PD72870B needs to gain access to the PCI-bus, assuming a clock rate of 33 MHz. Resolution is in units of ¼ μ s. The value should be loaded into the register from the external serial EEPROM after hardware reset, and access to this register through PCI-bus is prohibited.

Bits	R/W	Description
7-0	R	Default value of 00H. Its value contributes to the desired setting for Latency Timer value.

3.1.20 Offset_40 PCI_OHCI_Control Register

This register specifies the control bits that are IEEE1394 OpenHCl specific. Vendor options are not allowed in this register. It is reserved for OpenHCl use only.

Bits	R/W	Description
0	R/W	PCI global SWAP Default value of 0. When this bit is 1, all quadrates read from and written to
		the PCI Interface are byte swapped, thus a "PCI Global Swap". PCI addresses for expansion
		ROM and PCI Configuration registers, are, however, unaffected by this bit. This bit is not
		required for motherboard implementations.
31-1	R	Reserved Constant value of all 0.



3.1.21 Offset_60 Cap_ID & Next_Item_Ptr Register

The Cap_ID signals that this item in the Linked List is the registers defined for PCI Power Management, while the Next_Item_Ptr describes the location of the next item in the μ PD72870B's Capability List.

Bits	R/W	Description
7-0	R	Cap_ID Constant value of 01H. The default value identified the Link List item as being the PCI
		Power Management registers, while the ID value is assigned by the PCI SIG.
15-8	R	Next_Item_Ptr Constant value of 00H. It indicated that there are no more items in the Link
		List.

3.1.22 Offset_62 Power Management Capabilities Register

This is a 16-bit read-only register that provides information on the power management capabilities of the μ PD72870B.

Bits	R/W	Description
2-0	R	version Constant value of 010. The power management registers are implemented as defined
		in revision 1.1 of PCI Bus Power Management Interface Specification.
3	R	PME clock Constant value of 0.
4	R	Reserved Constant value of 0.
5	R	DIS Constant value of 0.
8-6	R	Auxiliary power source Constant value of 000. The alternative power source is not supported.
9	R	D1_support Constant value of 0. The μPD72870B does not support the D1 Power
		Management state.
10	R	D2_support Constant value of 1. The μ PD72870B supports the D2 Power Management state.
15-11	R	PME_support Constant value of 01100.



3.1.23 Offset_64 Power Management Control/Status Register

This is a 16-bit read-only register that provides control status information of the μ PD72870B.

Bits	R/W	Description
1,0	R/W	 PowerState Default value is undefined. This field is used both to determine the current power state of the μPD72870B and to set the μPD72870B into a new power state. As D1 is not supported in the current implementation of the μPD72870B, writing of '01' will be ignored. 00: D0 (DMA contexts: ON, Link Layer: ON) 01: Reserved (D1 state not supported) 10: D2 (DMA contexts: OFF, Link Layer: OFF, LPS: OFF, PME will be asserted upon LinkON being active) 11: D3 (DMA contexts: OFF, Link Layer: OFF, LPS: OFF, PME will be asserted upon LinkON being active, Power can be removed) The LPS is a PHY/Link interface signal and is defined in P1394a draft 2.0. It is an internal signal in the μPD72870B.
7-2	R	Reserved Constant value of 000000.
8	R/W	PME_En Default value of 0. This field is used to enable the specific power management features of the μ PD72870B.
12-9	R	Data_Select Constant value of 0000.
14,13	R	Data_Scale Constant value of 00.
15	R/W	PME_Status Default value is undefined. A write of '1' clears this bit, while a write of '0' is ignored.



3.2 CardBus Mode Configuration Register (CARD_ON = High)

31 2	4 23 16	15 08	07 00
De	vice ID	Ver	ndor ID
5	Status	Con	nmand
	Class Code		Revision ID
BIST	Header Type	Latency Timer	Cache Line Size
	Base A	Address 0	
	Base Address 1 (Ca	rdBus Status Reg) Note	
	Base Address 2 (Ca	rdBus Status Reg) Note	
	Base A	Address 3	
	Base A	Address 4	
	Base A	Address 5	
	CardBus C	S Pointer Note	
Subs	ystem ID	Subsyste	m Vendor ID
	Expansion Rom Ba	ase Address Register	
	000000H		Cap_Ptr
	0000	00000H	
Max_Lat	Min_Gnt	Interrupt Pin	Interrupt Line
	PCI_OH	CI_Control	
	0000	H00000	
	0000	00000H	
	0000	00000H	
	Diagnosi	ic register0	
	Diagnosi	ic register1	
	Diagnosi	ic register2	
	Diagnosi	ic register3	
Power Manag	ement Capabilities	Next_Item_Ptr	Cap_ID
Data	PMCSR_BSE	Power Managen	nent Control/Status
	0000	00000H	
	0000	00000H	
	0000	00000H	
	User Area (GEN	IERAL_RegisterB)	
	User Area (GEN	IERAL_RegisterC)	
	User Area (GEN	IERAL_RegisterD)	
	CIS A	rea Note	

Note Different from PCI Bus Mode Configuration Register.



3.2.1 Offset_14/18 Base_Address_1/2 Register (Cardbus Status Registers)

Bits	R/W	Description		
7-0	R	Constant value of 00.		
31-8	R/W	-		

(1) Function Event Register (FER) (Base Address 1 (2)+ 0H)

Bits	R/W	Description			
0	R	Write Protect (No Use).			
		Read only as '0'			
1	R	Ready Status (No Use).			
		Read only as '0'			
2	R	Battery Voltage Detect 2 (No Use).			
		Read only as '0'			
3	R	Battery Voltage Detect 1 (No Use).			
		Read only as '0'			
4	R/W	General Wakeup			
14-5	R	Reserved. Read only as '0'			
15	R/W	Interrupt			
31-16	R	Reserved. Read only as '0'			

(2) Function Event Mask Register (FEMR) (Base Address 1 (2)+4H)

Bits	R/W	Description		
0	R	Write Protect (No Use).		
		Read only as '0'		
1	R	Ready Status (No Use).		
		Read only as '0'		
2	R Battery Voltage Detect 2 (No Use).			
		Read only as '0'		
3	R Battery Voltage Detect 1 (No Use).			
		Read only as '0'		
4	R/W	General Wakeup Mask		
5	R	BAM. Read only as '0'		
6	R	PWM. Read only as '0'		
13-7	R	Reserved. Read only as '0'		
14	R/W	Wakeup Mask		
15	R/W	Interrupt		
31-16	R	Reserved. Read only as '0'		



(3) Function Reset Status Register (FRSR) (Base Address 1 (2)+8H)

Bits	R/W	Description		
0	R	Write Protect (No Use).		
		Read only as '0'		
1	R	Ready Status (No Use).		
		Read only as '0'		
2	R	Battery Voltage Detect 2 (No Use).		
		Read only as '0'		
3	R	Battery Voltage Detect 1 (No Use).		
		Read only as '0'		
4	R/W	General Wakeup Mask		
14-5	R	Reserved. Read only as '0'		
15	R/W	Interrupt		
31-16	R	Reserved. Read only as '0'		

(4) Function Force Event Register (FFER) (Base Address 1 (2)+ CH)

Bits	R/W	Description			
0	R	Write Protect (No Use).			
		Read only as '0'			
1	R	Ready Status (No Use).			
		Read only as '0'			
2	R	Battery Voltage Detect 2 (No Use).			
		Read only as '0'			
3	R	Battery Voltage Detect 1 (No Use).			
		Read only as '0'			
4	R/W	General Wakeup Mask			
14-5	-	No Use			
15	R/W	Interrupt			
31-16	R	Reserved. Read only as '0'			

3.2.2 Offset_28 Cardbus CIS Pointer

This register specifies start memory address of the Cardbus CIS Area.

Bits	R/W	Description		
31-0	R	Starting Pointer of CIS Area.		
		Constant value of 00000080H.		

3.2.3 Offset_80 CIS Area

The μ PD72870B supports external Serial ROM (AT24C02 compatible) interface.

CIS Area Register can be loaded from external Serial ROM in the CIS area when CARD_ON is 1.

CARD_ON	CIS_ON	Bus	CIS	Function
0	1	PCI	Off	PME
0	0	PCI	On	CSTSCHG
1	X	Cardbus	On	CSTSCHG

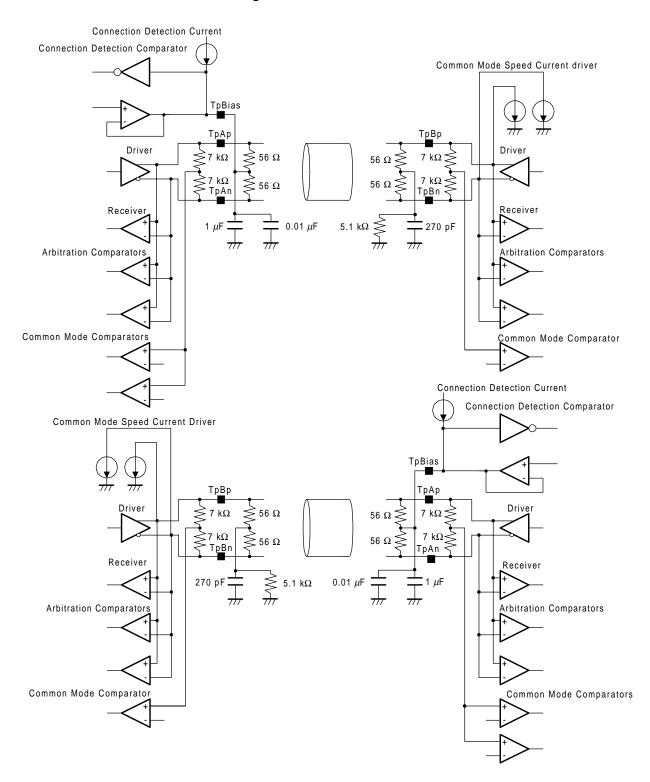


4. PHY FUNCTION

4.1 Cable Interface

4.1.1 Connections

Figure 4-1. Cable Interface





4.1.2 Cable Interface Circuit

Each port is configured with two twisted-pairs of TpA and TpB.

TpA and TpB are used to monitor the state of the Transmit/Receive line, control signals, data and cables.

During transmission to the IEEE1394 bus, the Data/Strobe signal received from the Link layer controller is encoded, converted from parallel to serial and transmitted.

While receiving from the IEEE1394 bus, the Data/Strobe signal from TpA, TpB is converted from serial to parallel after synchronization by SCLK Note, then transmitted to the Link layer controller in 2/4/8 bits according to the data rate of 100/200/400 Mbps.

The bus arbitration for TpA and TpB and the state of the line are monitored by the built-in comparator. The state of the 1394 bus is transmitted to the state machine in the LSI.

Note The SCLK is a PHY/Link interface signal and is defined in P1394a draft 2.0. It is an internal signal in the μ PD72870B.

4.1.3 CPS

An external resistance of 390 k Ω is connected in series to the power cable to monitor the power of the power cable. If the cable power falls under 7.5 V there is an indication to the Link layer that the power has failed.

4.1.4 Unused Ports

TpAp, TpAn: Not connected

TpBp, TpBn: AGND

TpBias : Connected to AGND using a 1.0 μ F load capacitor

No need to assemble the capacitor if using as Suspend/Resume On mode (SUS_RESM = 1).



4.2 Suspend/Resume

4.2.1 Suspend/Resume On Mode (SUS_RESM = 1)

There are two ways of transition from the active status to the suspended status.

One is when the receipt of a remote command packet that sets the initiate suspend command. After that, the PHY transmits a remote confirmation packet with the ok bit set, subsequently signals TX_SUSPEND to the connected peer PHY with the port which specified by the port field in the remote command packet, and then the PHY port transitions to the suspended state.

The other is when the receipt of a RX_SUSPEND or RX_DISABLE_NOTIFY signal. When the port observes RX_SUSPEND, it transmits TX_SUSPEND to the active ports.

The TX_SUSPEND transmitted propagates until it reaches a leaf node. The PHY port transitions to the suspended state. The propagation of the suspended domain may be blocked by a PHY compliant with IEEE Std 1394-1995, a disabled or a suspended port.

Any one of a number of reasons may cause a suspended port to attempt to resume normal operations:

- Bias is detected and there is no fault condition;
- A resume packet is received or transmitted by the PHY;
- A remote command packet that sets the resume port command is received; or
- Either port of a node without active ports detects bias.

4.2.2 Suspend/Resume Off Mode (SUS_RESM = 0)

- Remote command packet is ignored.
- Resume packet is ignored.
- Disabled, Int_enable and resume_int bits in PHY register are ignored.
- Responses to Remote access packet.
- Detects the connection of the port in TpBias.



4.3 PLL and Crystal Oscillation Circuit

4.3.1 Crystal Oscillation Circuit

To supply the clock of 24.576 MHz ± 100 ppm, use an external capacitor of 10 pF and a crystal of 50 ppm.

4.3.2 PLL

The crystal oscillator multiplies the 24.576 MHz frequency by 16 (393.216 MHz).

4.4 PC0-PC2, CMC

CMC shows the bus manager function which corresponds to the c bit of the Self_ID packet and the Contender bit in the PHY register when the input is High.

The value of CMC can be changed with software through the Link layer; this pin sets the initial value during Poweron Reset. Use a pull-up or pull-down resistor of 10 k Ω , based on the device's specification.

The PC0-PC2 pin corresponds to the power field of the Self_ID packet and Pwr_class in the PHY register. Refer to Section 4.3.4.1 of the IEEE1394-1995 specification for information regarding the Pwr_class. The value of Pwr can be changed with software through the Link layer; this pin sets the initial value during Power-on Reset. Use a pull-up or pull-down resistor of 10 k Ω based on the application.

4.5 P_RESETB

Connect an external capacitor of 0.1 μ F between the pins P_RESETB and GND. If the voltage drops below 0 V, a reset pulse is generated. All of the circuits are initialized, including the contents of the PHY register.

4.6 RI0, RI1

Connect an external resistor of 9.1 k Ω ± 0.5 % to limit the LSI's current.



5. SERIAL ROM INTERFACE

The μ PD72870B provides a serial ROM interface to initialize the 1394 Global Unique ID Register and the PCI/Cardbus Mode Configuration registers from a serial EEPROM.

The table 5-1 shows the serial EEPROM memory map required for initializing their registers.

5.1 Serial EEPROM Register

Register Address	Register Name	R/W
Base address + 0x930	SUBID register	R/W
Base address + 0x934	LATVAL register	R/W
Base address + 0x938	W_GUIDHi register	R/W
Base address + 0x93C	W_GUIDLo register	R/W
Base address + 0x940	Parameters Write register	R/W
Base address + 0x950	W_LAT register	R/W
Base address + 0x954	W_GENERAL register	R/W
Base address + 0x960	W_PHYS register	R/W
Base address + 0x980	W_CIS register	R/W

Remark Base address: Base Address 0 in Configuration register

5.2 Serial EEPROM Register Description

(1) SUBID register (Base address + 0x930)

31		10	15	0
	W_SUBSYSID		W_SUBVNDID	

Field	Bits	R/W	Default value	Description
W_SUBSYSID	31-16	R/W	0063H	Subsystem ID value. The value is loaded into Subsystem ID register in
				Configuration register (Offset+2CH bit 31-16).
W_SUBVNDID	15-0	R/W	1033H	Subsystem Vendor ID value. The value is loaded into Subsystem Vendor ID
				register in Configuration register (Offset+2CH bit 15-0).

(2) LATVAL register (Base address + 0x934)

31	24 23	16 15 12	11	10	4	3 0
W_MAXLAT	W_MINGNT	- 0 -	1	- 0 -		W_MAX_REC

Field	Bits	R/W	Default value	Description
W_MAXLAT	31-24	R/W	00H	Max Latency value. The value is loaded into Max Latency register in
				Configuration register (Offset+3CH bit 31-24).
W_MINGNT	23-16	R/W	00H	Min Grant value. The value is loaded into Min Grant register in Configuration
				register (Offset+3CH bit 23-16).
-	15-12	-	-	Reserved. Write 0 to these bits.
	11	-	-	Reserved. Write 1 to this bit.
	10-4	-	-	Reserved. Write 0 to these bits.
W_MAX_REC	3-0	R/W	9H	MAX_REC value. The value is loaded into the max_rec field of OHCI
				BusOption register in OHCl register (Offset+020H bit 15-12).



(3) W_GUIDHi register (Base address + 0x938)

_	31	0
	W_GUIDHi	

Field	Bits	R/W	Default value	Description
W_GUIDHi	31-0	R/W	Undefined	GlobalUniqueIDHi value. The value is loaded into OHCI GlobalUniqueIDHi
				register in OHCl register (Offset+024H bit 31-0).
				Please refer to the 1394 Open Host Controller Interface Specification/Release
				1.0 [5.5.5].

(4) W_GUIDLo register (Base address + 0x93C)

31		0
	W_GUIDLo	

Field	Bits	R/W	Default value	Description
W_GUIDLo	31-0	R/W	Undefined	GlobalUniqueIDLo value. The value is loaded into GlobalUniqueIDLo register
				in OHCI register (Offset+028H bit 31-0).
				Please refer to the 1394 Open Host Controller Interface Specification/Release
				1.0 [5.5.5].

(5) Parameters Write register (Base address + 0x940)

31		/	6	4	3	1	0
	- 0 -		PAGE_	S	- C) -	PAR _W

Field	Bits	R/W	Default value	Description					
-	31-7	-	-	Reserved. Write 0 to these bits.					
PAGE_S	6-4	R/W	000	Write register select page. The bit field returns zero when read.					
				000: Select SUBID register and LATVAL register.					
				001: Select W_GUIDHi register and W_GUIDLo register.					
				010: Select W_LAT register and W_GENERAL register (W_GENERAL_0					
				011: Select W_GENERAL register (W_GENERAL_1 and W_GENERAL_2)					
				100: Select W_PHYS register (W_ programPhyEnable,					
				W_aPhyEnhanceEnable).					
				101: Select W_CIS register (W_CIS_EVEN - W_CIS_ODD).					
-	3-1	-	-	Reserved. Write 0 to these bits.					
PAR_W	0	R/W	0	Write control signal. The bit field returns zeros when read.					
				1: Write the value of select page defined PAGE_S. One write transaction is					
				the units of 8 byte.					
				0: Ignored.					

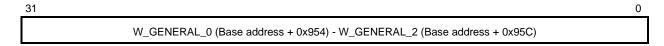


(6) W_LAT register (Base address + 0x950)

31 8	7	3	2 0	
- 0 -	W_LAT		- 0 -	Ī

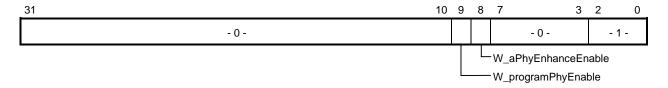
Field	Bits	R/W	Default value	Description
	31-8	ı	-	Reserved. Write 0 to these bits.
W_LAT	7-3	R/W	00000	Latency timer value. The value is loaded into Latency Timer in Configuration
				register (Offset+0CH bit 15-8) when using as Cardbus mode (CARD_ON = 1).
				It is not loaded when using as PCI bus mode (CARD_ON = 0).
-	2-0	-	-	Reserved. Write 0 to these bits.

(7) W_GENERAL register (Base address + 0x954 - 0x95C)



Field	Bits	R/W	Default value	Description
W_GENERAL_0 -	31-0	R/W	Undefined	User define value. The value is loaded into GENERAL_registerB - D in
W_GENERAL_2				Configuration register (Offset+70H - 7BH).

(8) W_PHYS register (Base address + 0x960)



Field	Bits	R/W	Default value	Description
-	31-10	-	-	Reserved. Write 0 to these bits.
W_programPhyEnable	9	R/W	1	programPhyEnable bit. The bit is loaded into HCControl registers in OHCI register ((Offset+50H bit 23) and (54H bit 23)). Please refer to the 1394 Open Host Controller Interface Specification/Release 1.0 [5.7].
				P1394a enhancement is supported. P1394a enhancement is not supported.
W_aPhyEnhanceEnable	8	R/W	0	aPhyEnhanceEnable bit. The bit is loaded into HCControl registers in OHCI register ((Offset+50H bit 23) and (54H bit 23)).
-	7-3	-	-	Reserved. Write 0 to these bits.
	2-0	-	-	Reserved. Write 1 to these bits.



(9) W_CIS register (Base address + 0x980 - 0x984)

31		0
	W_CIS_EVEN (Base address + 0x980) - W_CIS_ODD (Base address + 0x984)	

Field	Bits	R/W	Default value	Description
W_CIS_EVEN -	31-0	R/W	Undefined	CIS Area value. The value is loaded into CIS Area in Configuration register
W_CIS_ODD				(Offset+80H - FCH).



Table 5-1. Serial EEPROM Memory Map

Byte				В	it			
address	7	6	5	4	3	2	1	0
0				W_SUBSY:	SID(31 : 24)			
1				W_SUBSY:	SID(23 : 16)			
2				W_SUBVN	DID(15: 8)			
3				W_SUBVN	DID(7:0)			
4				W_MAXLA	AT(31 : 24)			
5				W_MINGN	NT(23 : 16)			
6	0	0	0	0	1	0	0	0
7	0	0	0	0		W_MAX_F	REC(3:0)	
8				W_GUIDI	Hi(31 : 24)			
9				W_GUIDI	Hi(23 : 16)			
Α				W_GUID	Hi(15: 8)			
В				W_GUID	Hi(7: 0)			
С				W_GUIDL	o(31 : 24)			
D				W_GUIDL	.o(23 : 16)			
Е				W_GUIDI	_o(15 : 8)			
F		W_GUIDLo(7 : 0)						
10	0	0	0	0	0	0	0	0
11	0	0	0	0	0	0	0	0
12	0	0	0	0	0	0	0	0
13		•	W_LAT(7: 3)			0	0	0
14		W_GENERAL_0(31 : 24)						
15	W_GENERAL_0(23 : 16)							
16	W_GENERAL_0(15 : 8)							
17	W_GENERAL_0(7: 0)							
:	:							
:	<u> </u>							
1C				W_GENERA	L_2(31 : 24)			
1D				W_GENERA	L_2(23 : 16)			
1E					AL_2(15: 8)			
1F				W_GENER	AL_2(7:0)			
20	0	0	0	0	0	0	0	0
21	0	0	0	0	0	0	0	0
22	0	0	0	0	0	0	WPE	WPEE
23	0	0	0	0	0	1	1	1
:					•			
:					!			
28				W_CIS_0				
29				W_CIS_0	· ,			
2A					0(15 : 8)			
2B				W_CIS_	0(7:0)			
:					•			
:	<u> </u>							
A4					1(31 : 24)			
A5					1(23 : 16)			
A6				W_CIS_3				
A7	W_CIS_31(7: 0)							

WPE: W_programPhyEnable, WPEE: W_aPhyEnhanceEnable



5.3 Load Control

GROM_EN	CARD_ON	CIS_ON	Description
0	Х	X	No loading.
1	0	1	W_SUBSYSID, W_SUBVNDID, W_MAXLAT, W_MINGNT, W_MAX_REC, W_GUIDHi/Lo,
			W_LAT, W_GENERAL_0 - W_GENERAL_2, W_programPhyEnable,
			W_aPhyEnhanceEnable are loaded.
1	0	0	All parameters (W_SUBSYSID, W_SUBVNDID, W_MAXLAT, W_MINGNT, W_MAX_REC,
		.,	W_GUIDHi/Lo, W_LAT, W_GENERAL_0 - W_GENERAL_2, W_programPhyEnable,
1	1	Х	W_aPhyEnhanceEnable, W_CIS_EVEN - W_CIS_ODD) are loaded.

5.4 Programming Sequence Example

The example of programming sequence to the serial EEPROM is shown below.

- (1) Write SUBID register. Note1
- (2) Write LATVAL register. Note1
- (3) Write PAGE_S = 000 and PAR_W = 1 on Parameters Write register. Note1
- (4) Wait over 13 ms for serial EEPROM access time. Note1
- (5) Write W_GUIDHi register. Note2
- (6) Write W_GUIDLo register. Note2
- (7) Write PAGE_S = 001 and PAR_W = 1 on Parameters Write register. Note2
- (8) Wait over 13 ms for serial EEPROM access time. Note2
- (9) Write W_LAT register. Note3
- (10) Write W_GENERAL register (W_GENERAL_0). Note3
- (11) Write PAGE_S = 010 and PAR_W = 1 on Parameters Write register. Note3
- (12) Wait over 13 ms for serial EEPROM access time. Note3
- (13) Write W_GENERAL register (W_GENERAL_1, W_GENERAL_2). Note4
- (14) Write PAGE_S = 011 and PAR_W = 1 on Parameters Write register. Note4
- (15) Wait over 13 ms for serial EEPROM access time. Note4
- (16) Write W_CIS register. Note5
- (17) Write PAGE_S = 100 and PAR_W = 1 on Parameters Write register. Note5
- (18) Wait over 30 ms for serial EEPROM access time. Note5
- (19) Complete to write parameters into Serial EEPROM.
- (20) Parameters are loaded from serial EEPROM after PCI reset.
- **Notes 1.** If none of W_SUBSYSED, W_SUBVNDID, W_MAXLAT, W_MINGNT, W_HOLD_TIMER, W_MAX_REC in serial EEPROM are changed, (1)-(4) transactions don't need.
 - 2. If none of W_GUIDHi, W_GUIDLo in serial EEPROM are changed, (5)-(8) transactions don't need.
 - 3. If none of W_LAT, W_GENERAL_0 in serial EEPROM are changed, (9)-(12) transactions don't need.
 - **4.** If none of W_GENERAL_1, W_GENERAL_2 in serial EEPROM are changed, (13)-(15) transactions don't need.
 - **5.** If none of W_CIS_0 W_CIS_31 in serial EEPROM are changed, (16)-(18) transactions don't need. One write transaction (Parameters Write register: PAGE_S = 100 and PAR_W = 1) is the units of 8 byte. If more than 8 byte write, you need to repeat (16)-(18). *



- *: Write W_CIS_0, W_CIS_1 register.
 - Write PAGE_S = 100 and PAR_W = 1 on Parameters Write register.
 - Wait over 30 ms for serial EEPROM access time.

:

- Write W_CIS_30, W_CIS_31 register.
- Write PAGE_S = 100 and PAR_W = 1 on Parameters Write register.
- Wait over 30 ms for serial EEPROM access time.



6. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage	V _{DD}		-0.5 to +4.6	V
Input voltage	Vı	LVTTL @ (V1 < 0.5 V + VDD)	-0.5 to +4.6	V
		PCI @ (VI < 3.0 V + VDD)	-0.5 to +6.6	V
Output voltage	Vo	LVTTL @ (Vo < 0.5 V + VDD)	-0.5 to +4.6	V
		PCI @ (Vo < 3.0 V + VDD)	-0.5 to +6.6	V
Operating ambient temperature	TA		0 to +70	°C
Storage temperature	T _{stg}		-65 to +150	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Recommended Operating Ranges

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage	V _{DD}	Used to clamp reflection on PCI bus.	4.5 to 5.5	V
			3.0 to 3.6	V
Operating ambient temperature	TA		0 to +70	°C



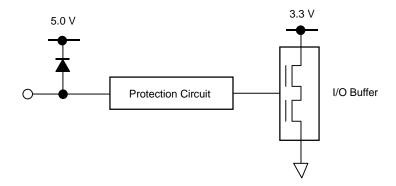
DC Characteristics (V_{DD} = 3.3 V \pm 10 %, V_{SS} = 0 V, T_A = 0 to +70°C)

Parameter	Symbol		Condition	MIN.	TYP.	MAX.	Unit
High-level input voltage	VIH			2.0		V _{DD} +0.5	V
Low-level input voltage	Vıl			-0.5		+0.8	V
High-level output current	Іон	Vон	Pin No.153,154	-6			mA
		=2.4 V	Pin No.74,76-79,83,84,92	-9			mA
Low-level output current	loL	Vol	Pin No.153,154	6			mA
		=0.4 V	Pin No.74,76-79,83,84,92	9			mA
Input leakage current	l∟	VIN =	VDD or GND			±10.0	μΑ
Supply current	IDD	3 por	s, S400, V _{DD} = 3.3 V			280	mA
PCI interface							
High-level input voltage	ViH			2.0		5.5	V
Low-level input voltage	VIL			-0.5		+0.8	V
High-level output current	Іон	Vон =	= 2.4 V	-2			mA
Low-level output current	loL	Vol =	0.4 V	9			mA
Input leakage current	lι	VIN =	VDD or GND			±10.0	μΑ
Cable interface							
Differential input voltage	VID	Cable i	nput, 100 Mbps operation	142		260	mV
		Cable i	nput, 200 Mbps operation	132		260	mV
		Cable i	nput, 400 Mbps operation	118		260	mV
TpB common mode input voltage	Vісм	100 M	bps speed signaling off	1.165		2.515	V
		200 M	bps speed signaling	0.935		2.515	V
		400 M	bps speed signaling	0.523		2.515	V
Differential output voltage	Vod	Cable	output (Test load 55Ω)	172.0		265.0	mV
TpA common mode output voltage	Vосм	100 M	bps speed signaling off	1.665		2.015	V
		200 M	bps speed signaling	1.438		2.015	V
		400 M	bps speed signaling	1.030		2.015	V
TpA common mode output current	Ісм	100 M	bps speed signaling off	-0.81		+0.44	mA
		200 M	bps speed signaling	-4.84		-2.53	mA
		400 M	bps speed signaling	-12.40		-8.10	mA
Power status threshold voltage	Vтн	CPS				7.5	V
TpBias output voltage	VTPBIAS			1.665		2.015	V



Remarks 1. Digital core runs at 3.3 V.

- 2. PCI Interface can run at 5 or 3.3 V, depending on the choice of 5 V-PCI or 3.3 V-PCI.
- 3. All other I/Os are 3.3 V driving, and 5 V tolerant.
- 4. 5 V are used only for 5 V-PCI clamping diode.



AC Characteristics

PCI Interface

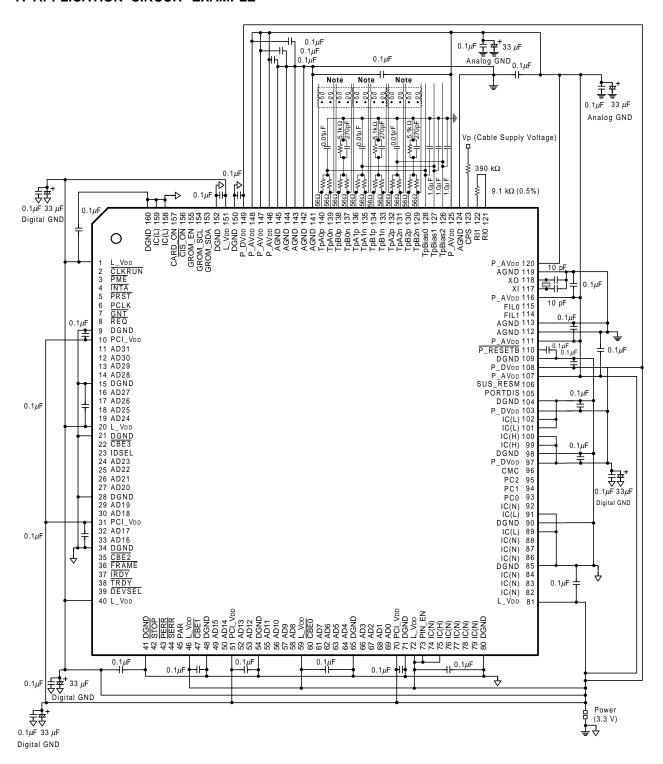
See PCI local bus specification Revision 2.1.

Serial ROM Interface

See AT24C01A/02/04/08/16 Spec. Sheet.



7. APPLICATION CIRCUIT EXAMPLE



Note Common mode choke.

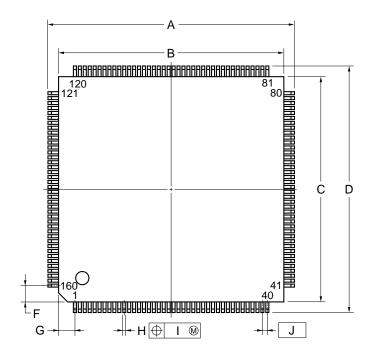
Recommendation : TOKO Part No. 857CM-0009 (TYPE B5W)

: MURATA Part No. PLW3216S161SQ2

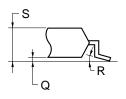


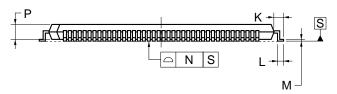
8. PACKAGE DRAWINGS

160-PIN PLASTIC LQFP (FINE PITCH) (24x24)



detail of lead end





NOTE

Each lead centerline is located within 0.10 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
Α	26.0±0.2
В	24.0±0.2
С	24.0±0.2
D	26.0±0.2
F	2.25
G	2.25
Н	$0.22^{+0.05}_{-0.04}$
I	0.10
J	0.5 (T.P.)
K	1.0±0.2
L	0.5±0.2
М	$0.145^{+0.055}_{-0.045}$
N	0.10
Р	1.4±0.1
Q	0.125±0.075
R	3°+7°
S	1.7 MAX.

S160GM-50-8ED-3



NOTES FOR CMOS DEVICES

(1) PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

(2) HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

(3) STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.



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- NEC semiconductor products are classified into the following three quality grades:
 - "Standard", "Special" and "Specific". The "Specific" quality grade applies only to semiconductor products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of a semiconductor product depend on its quality grade, as indicated below. Customers must check the quality grade of each semiconductor product before using it in a particular application.
 - "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
 - "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
 - "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC semiconductor products is "Standard" unless otherwise expressly specified in NEC's data sheets or data books, etc. If customers wish to use NEC semiconductor products in applications not intended by NEC, they must contact an NEC sales representative in advance to determine NEC's willingness to support a given application.

(Note)

- (1) "NEC" as used in this statement means NEC Corporation and also includes its majority-owned subsidiaries.
- (2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).